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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	27
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21332cnfp-30

Table 1.2 Specifications for R8C/33C Group (2)

Item	Function	Specification
Serial Interface	UART0, UART1	Clock synchronous serial I/O/UART × 2 channel
	UART2	Clock synchronous serial I/O/UART, I ² C mode (I ² C-bus), multiprocessor communication function
Synchronous Serial Communication Unit (SSU)		1 (shared with I ² C-bus)
I ² C bus		1 (shared with SSU)
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function, with sweep mode
D/A Converter		8-bit resolution × 2 circuits
Comparator B		2 circuits
Flash Memory		• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function • Background operation (BGO) function
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 1.8 to 5.5 V)
Current Consumption		Typ. 6.5 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 3.5 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 2.0 μA (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		-20 to 85°C (N version) -40 to 85°C (D version) ⁽¹⁾
Package		32-pin LQFP Package code: PLQP0032GB-A (previous code: 32P6U-A)

Note:

1. Specify the D version if D version functions are to be used.

3. Memory

3.1 R8C/33C Group

Figure 3.1 is a Memory Map of R8C/33C Group. The R8C/33C Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 32-Kbyte internal ROM area is allocated addresses 08000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.

The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM area is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh. Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.

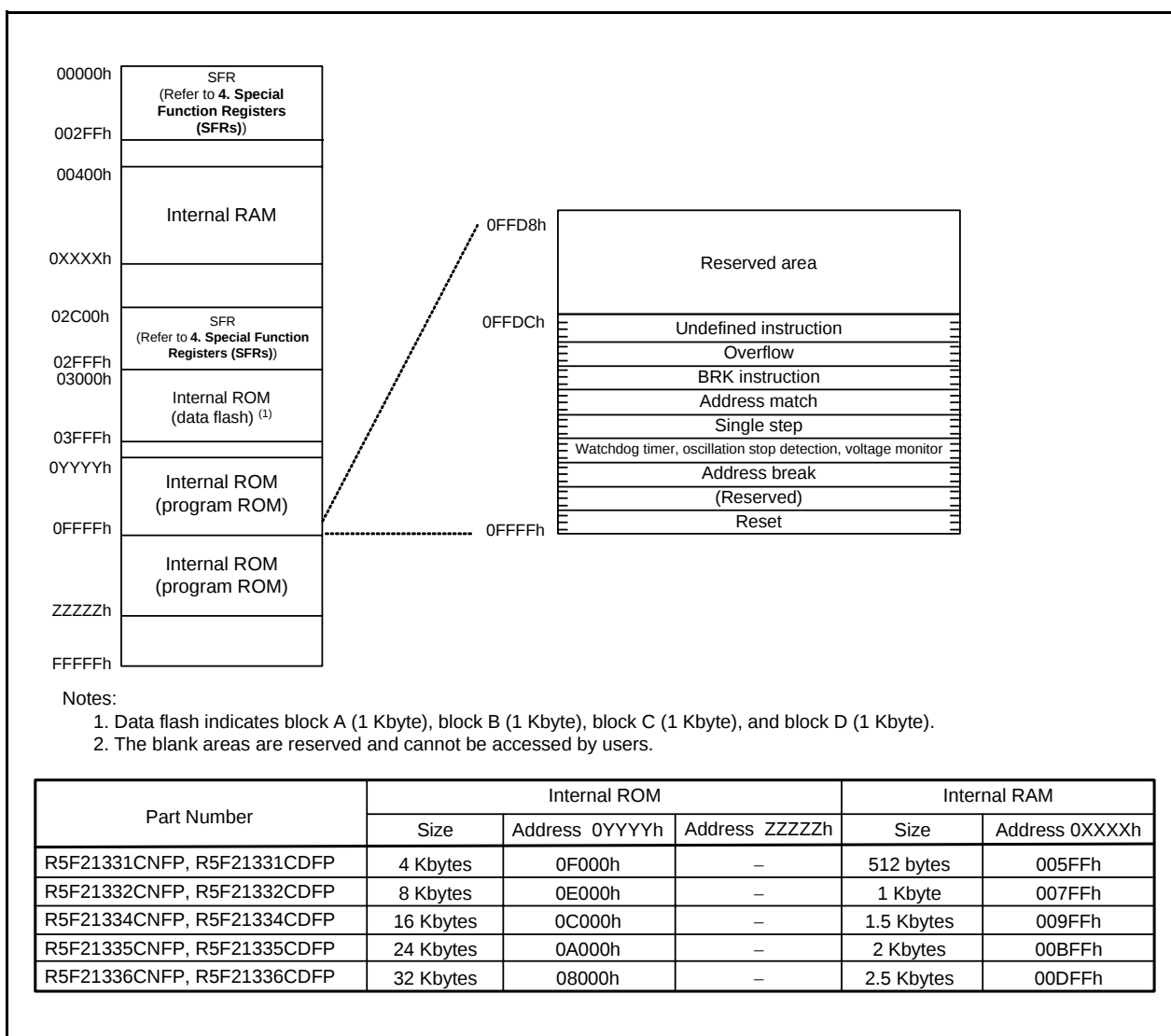


Figure 3.1 Memory Map of R8C/33C Group

Table 4.4 SFR Information (4) ⁽¹⁾

Address	Register	Symbol	After Reset
00C0h	A/D Register 0	AD0	XXh
00C1h			000000XXb
00C2h	A/D Register 1	AD1	XXh
00C3h			000000XXb
00C4h	A/D Register 2	AD2	XXh
00C5h			000000XXb
00C6h	A/D Register 3	AD3	XXh
00C7h			000000XXb
00C8h	A/D Register 4	AD4	XXh
00C9h			000000XXb
00CAh	A/D Register 5	AD5	XXh
00CBh			000000XXb
00CCh	A/D Register 6	AD6	XXh
00CDh			000000XXb
00CEh	A/D Register 7	AD7	XXh
00CFh			000000XXb
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Mode Register	ADMOD	00h
00D5h	A/D Input Select Register	ADINSEL	11000000b
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h	D/A0 Register	DA0	00h
00D9h	D/A1 Register	DA1	00h
00DAh			
00DBh			
00DCh	D/A Control Register	DACON	00h
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh			
00EDh			
00EEh			
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.5 SFR Information (5) (1)

Address	Register	Symbol	After Reset
0100h	Timer RA Control Register	TRACR	00h
0101h	Timer RA I/O Control Register	TRAIOC	00h
0102h	Timer RA Mode Register	TRAMR	00h
0103h	Timer RA Prescaler Register	TRAPRE	FFh
0104h	Timer RA Register	TRA	FFh
0105h	LIN Control Register 2	LINCR2	00h
0106h	LIN Control Register	LINCR	00h
0107h	LIN Status Register	LINST	00h
0108h	Timer RB Control Register	TRBCR	00h
0109h	Timer RB One-Shot Control Register	TRBOCR	00h
010Ah	Timer RB I/O Control Register	TRBIOC	00h
010Bh	Timer RB Mode Register	TRBMR	00h
010Ch	Timer RB Prescaler Register	TRBPRES	FFh
010Dh	Timer RB Secondary Register	TRBSC	FFh
010Eh	Timer RB Primary Register	TRBPR	FFh
010Fh			
0110h			
0111h			
0112h			
0113h			
0114h			
0115h			
0116h			
0117h			
0118h	Timer RE Second Data Register / Counter Data Register	TRESEC	00h
0119h	Timer RE Minute Data Register / Compare Data Register	TREMIN	00h
011Ah	Timer RE Hour Data Register	TREHR	00h
011Bh	Timer RE Day of Week Data Register	TREWK	00h
011Ch	Timer RE Control Register 1	TRECR1	00h
011Dh	Timer RE Control Register 2	TRECR2	00h
011Eh	Timer RE Count Source Select Register	TRECSR	00001000b
011Fh			
0120h	Timer RC Mode Register	TRCMR	01001000b
0121h	Timer RC Control Register 1	TRCCR1	00h
0122h	Timer RC Interrupt Enable Register	TRCIER	01110000b
0123h	Timer RC Status Register	TRCSR	01110000b
0124h	Timer RC I/O Control Register 0	TRCIOR0	10001000b
0125h	Timer RC I/O Control Register 1	TRCIOR1	10001000b
0126h	Timer RC Counter	TRC	00h
0127h			00h
0128h	Timer RC General Register A	TRCGRA	FFh
0129h			FFh
012Ah	Timer RC General Register B	TRCGRB	FFh
012Bh			FFh
012Ch	Timer RC General Register C	TRCGRC	FFh
012Dh			FFh
012Eh	Timer RC General Register D	TRCGRD	FFh
012Fh			FFh
0130h	Timer RC Control Register 2	TRCCR2	00011000b
0131h	Timer RC Digital Filter Function Select Register	TRCDF	00h
0132h	Timer RC Output Master Enable Register	TRCOER	01111111b
0133h	Timer RC Trigger Control Register	TRCADCR	00h
0134h			
0135h			
0136h			
0137h			
0138h			
0139h			
013Ah			
013Bh			
013Ch			
013Dh			
013Eh			
013Fh			

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.6 SFR Information (6) ⁽¹⁾

Address	Register	Symbol	After Reset
0140h			
0141h			
0142h			
0143h			
0144h			
0145h			
0146h			
0147h			
0148h			
0149h			
014Ah			
014Bh			
014Ch			
014Dh			
014Eh			
014Fh			
0150h			
0151h			
0152h			
0153h			
0154h			
0155h			
0156h			
0157h			
0158h			
0159h			
015Ah			
015Bh			
015Ch			
015Dh			
015Eh			
015Fh			
0160h	UART1 Transmit/Receive Mode Register	U1MR	00h
0161h	UART1 Bit Rate Register	U1BRG	XXh
0162h	UART1 Transmit Buffer Register	U1TB	XXh
0163h			XXh
0164h	UART1 Transmit/Receive Control Register 0	U1C0	00001000b
0165h	UART1 Transmit/Receive Control Register 1	U1C1	00000010b
0166h	UART1 Receive Buffer Register	U1RB	XXh
0167h			XXh
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h			
0171h			
0172h			
0173h			
0174h			
0175h			
0176h			
0177h			
0178h			
0179h			
017Ah			
017Bh			
017Ch			
017Dh			
017Eh			
017Fh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.7 SFR Information (7) ⁽¹⁾

Address	Register	Symbol	After Reset
0180h	Timer RA Pin Select Register	TRASR	00h
0181h	Timer RB/RC Pin Select Register	TRBRCSR	00h
0182h	Timer RC Pin Select Register 0	TRCPSR0	00h
0183h	Timer RC Pin Select Register 1	TRCPSR1	00h
0184h			
0185h			
0186h			
0187h			
0188h	UART0 Pin Select Register	U0SR	00h
0189h	UART1 Pin Select Register	U1SR	00h
018Ah	UART2 Pin Select Register 0	U2SR0	00h
018Bh	UART2 Pin Select Register 1	U2SR1	00h
018Ch	SSU/IIC Pin Select Register	SSUICSR	00h
018Dh			
018Eh	INT Interrupt Input Pin Select Register	INTSR	00h
018Fh	I/O Function Pin Select Register	PINSR	00h
0190h			
0191h			
0192h			
0193h	SS Bit Counter Register	SSBR	11111000b
0194h	SS Transmit Data Register L / IIC bus Transmit Data Register ⁽²⁾	SSTDR / ICDRT	FFh
0195h	SS Transmit Data Register H ⁽²⁾	SSTDRH	FFh
0196h	SS Receive Data Register L / IIC bus Receive Data Register ⁽²⁾	SSRDR / ICDRR	FFh
0197h	SS Receive Data Register H ⁽²⁾	SSRDRH	FFh
0198h	SS Control Register H / IIC bus Control Register 1 ⁽²⁾	SSCRH / ICCR1	00h
0199h	SS Control Register L / IIC bus Control Register 2 ⁽²⁾	SSCRL / ICCR2	01111101b
019Ah	SS Mode Register / IIC bus Mode Register ⁽²⁾	SSMR / ICMR	00010000b / 00011000b
019Bh	SS Enable Register / IIC bus Interrupt Enable Register ⁽²⁾	SSER / ICIER	00h
019Ch	SS Status Register / IIC bus Status Register ⁽²⁾	SSSR / ICSR	00h / 0000X000b
019Dh	SS Mode Register 2 / Slave Address Register ⁽²⁾	SSMR2 / SAR	00h
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h	Flash Memory Status Register	FST	10000X00b
01B3h			
01B4h	Flash Memory Control Register 0	FMR0	00h
01B5h	Flash Memory Control Register 1	FMR1	00h
01B6h	Flash Memory Control Register 2	FMR2	00h
01B7h			
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			

X: Undefined

Notes:

1. The blank areas are reserved and cannot be accessed by users.
2. Selectable by the IICSEL bit in the SSUICSR register.

Table 4.12 SFR Information (12) (1)

Address	Register	Symbol	After Reset
2CF0h	DTC Control Data 22	DTCD22	XXh
2CF1h			XXh
2CF2h			XXh
2CF3h			XXh
2CF4h			XXh
2CF5h			XXh
2CF6h			XXh
2CF7h			XXh
2CF8h	DTC Control Data 23	DTCD23	XXh
2CF9h			XXh
2CFAh			XXh
2CFBh			XXh
2CFCh			XXh
2CFDh			XXh
2CFEh			XXh
2CFFh			XXh
2D00h			
⋮			
2FFFh			

X: Undefined

Note:

- The blank areas are reserved and cannot be accessed by users.

Table 4.13 ID Code Areas and Option Function Select Area

Address	Area Name	Symbol	After Reset
⋮			
FFDBh	Option Function Select Register 2	OFS2	(Note 1)
⋮			
FFDFh	ID1		(Note 2)
⋮			
FFE3h	ID2		(Note 2)
⋮			
FFEBh	ID3		(Note 2)
⋮			
FFEFh	ID4		(Note 2)
⋮			
FFF3h	ID5		(Note 2)
⋮			
FFF7h	ID6		(Note 2)
⋮			
FFFBh	ID7		(Note 2)
⋮			
FFFFh	Option Function Select Register	OFS	(Note 1)

Notes:

- The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not write additions to the option function select area. If the block including the option function select area is erased, the option function select area is set to FFh. When blank products are shipped, the option function select area is set to FFh. It is set to the written value after written by the user. When factory-programming products are shipped, the value of the option function select area is the value programmed by the user.
- The ID code areas are allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not write additions to the ID code areas. If the block including the ID code areas is erased, the ID code areas are set to FFh. When blank products are shipped, the ID code areas are set to FFh. They are set to the written value after written by the user. When factory-programming products are shipped, the value of the ID code areas is the value programmed by the user.

Table 5.2 Recommended Operating Conditions

Symbol	Parameter				Conditions	Standard			Unit
						Min.	Typ.	Max.	
V _{CC} /AV _{CC}	Supply voltage					1.8	–	5.5	V
V _{SS} /AV _{SS}	Supply voltage					–	0	–	V
V _{IH}	Input “H” voltage	Other than CMOS input				0.8 V _{CC}	–	V _{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0.5 V _{CC}	–	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.55 V _{CC}	–	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.65 V _{CC}	–	V _{CC}	V
			Input level selection : 0.5 V _{CC}		4.0 V ≤ V _{CC} ≤ 5.5 V	0.65 V _{CC}	–	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.7 V _{CC}	–	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.8 V _{CC}	–	V _{CC}	V
			Input level selection : 0.7 V _{CC}		4.0 V ≤ V _{CC} ≤ 5.5 V	0.85 V _{CC}	–	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.85 V _{CC}	–	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.85 V _{CC}	–	V _{CC}	V
		External clock input (XOUT)				1.2	–	V _{CC}	V
V _{IL}	Input “L” voltage	Other than CMOS input				0	–	0.2 V _{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0	–	0.2 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	–	0.2 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	–	0.2 V _{CC}	V
			Input level selection : 0.5 V _{CC}		4.0 V ≤ V _{CC} ≤ 5.5 V	0	–	0.4 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	–	0.3 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	–	0.2 V _{CC}	V
			Input level selection : 0.7 V _{CC}		4.0 V ≤ V _{CC} ≤ 5.5 V	0	–	0.55 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	–	0.45 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	–	0.35 V _{CC}	V
		External clock input (XOUT)				0	–	0.4	V
I _{OH} (sum)	Peak sum output “H” current	Sum of all pins I _{OH} (peak)				–	–	–160	mA
I _{OH} (sum)	Average sum output “H” current	Sum of all pins I _{OH} (avg)				–	–	–80	mA
I _{OH} (peak)	Peak output “H” current	Drive capacity Low				–	–	–10	mA
		Drive capacity High				–	–	–40	mA
I _{OH} (avg)	Average output “H” current	Drive capacity Low				–	–	–5	mA
		Drive capacity High				–	–	–20	mA
I _{OL} (sum)	Peak sum output “L” current	Sum of all pins I _{OL} (peak)				–	–	160	mA
I _{OL} (sum)	Average sum output “L” current	Sum of all pins I _{OL} (avg)				–	–	80	mA
I _{OL} (peak)	Peak output “L” current	Drive capacity Low				–	–	10	mA
		Drive capacity High				–	–	40	mA
I _{OL} (avg)	Average output “L” current	Drive capacity Low				–	–	5	mA
		Drive capacity High				–	–	20	mA
f _(XIN)	XIN clock input oscillation frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	–	–	5	MHz
f _(XCIN)	XCIN clock input oscillation frequency				1.8 V ≤ V _{CC} ≤ 5.5 V	–	32.768	50	kHz
f _{OCO40M}	When used as the count source for timer RC ⁽³⁾				2.7 V ≤ V _{CC} ≤ 5.5 V	32	–	40	MHz
f _{OCO-F}	f _{OCO-F} frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	–	–	5	MHz
–	System clock frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	–	–	5	MHz
f _(BCLK)	CPU clock frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	–	–	5	MHz

Notes:

1. V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. The average output current indicates the average value of current measured during 100 ms.
3. f_{OCO40M} can be used as the count source for timer RC in the range of V_{CC} = 2.7 V to 5.5 V.

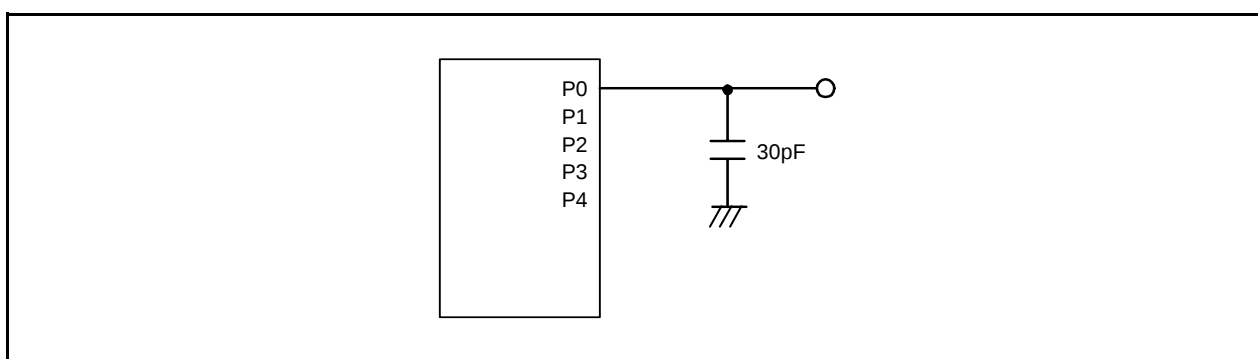


Figure 5.1 Ports P0 to P4 Timing Measurement Circuit

Table 5.3 A/D Converter Characteristics

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
—	Resolution		Vref = AVCC		—	—	10	Bit
—	Absolute accuracy	10-bit mode	Vref = AVCC = 5.0 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±3	LSB
			Vref = AVCC = 3.3 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±5	LSB
			Vref = AVCC = 3.0 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±5	LSB
			Vref = AVCC = 2.2 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±5	LSB
		8-bit mode	Vref = AVCC = 5.0 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±2	LSB
			Vref = AVCC = 3.3 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±2	LSB
			Vref = AVCC = 3.0 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±2	LSB
			Vref = AVCC = 2.2 V	AN0 to AN7 input, AN8 to AN11 input	—	—	±2	LSB
φAD	A/D conversion clock		4.0 ≤ Vref = AVCC ≤ 5.5 V (2)		2	—	20	MHz
			3.2 ≤ Vref = AVCC ≤ 5.5 V (2)		2	—	16	MHz
			2.7 ≤ Vref = AVCC ≤ 5.5 V (2)		2	—	10	MHz
			2.2 ≤ Vref = AVCC ≤ 5.5 V (2)		2	—	5	MHz
—	Tolerance level impedance				—	3	—	kΩ
tCONV	Conversion time	10-bit mode	Vref = AVCC = 5.0 V, φAD = 20 MHz		2.2	—	—	μs
		8-bit mode	Vref = AVCC = 5.0 V, φAD = 20 MHz		2.2	—	—	μs
tsAMP	Sampling time		φAD = 20 MHz		0.8	—	—	μs
Ivref	Vref current		Vcc = 5 V, XIN = f1 = φAD = 20 MHz		—	45	—	μA
Vref	Reference voltage				2.2	—	AVCC	V
VIA	Analog input voltage (3)				0	—	Vref	V
OCVREF	On-chip reference voltage		2 MHz ≤ φAD ≤ 4 MHz		1.19	1.34	1.49	V

Notes:

- $V_{CC}/AV_{CC} = V_{ref} = 2.2$ to 5.5 V , $V_{SS} = 0\text{ V}$ and $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
- The A/D conversion result will be undefined in wait mode, stop mode, when the flash memory stops, and in low-current-consumption mode. Do not perform A/D conversion in these states or transition to these states during A/D conversion.
- When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

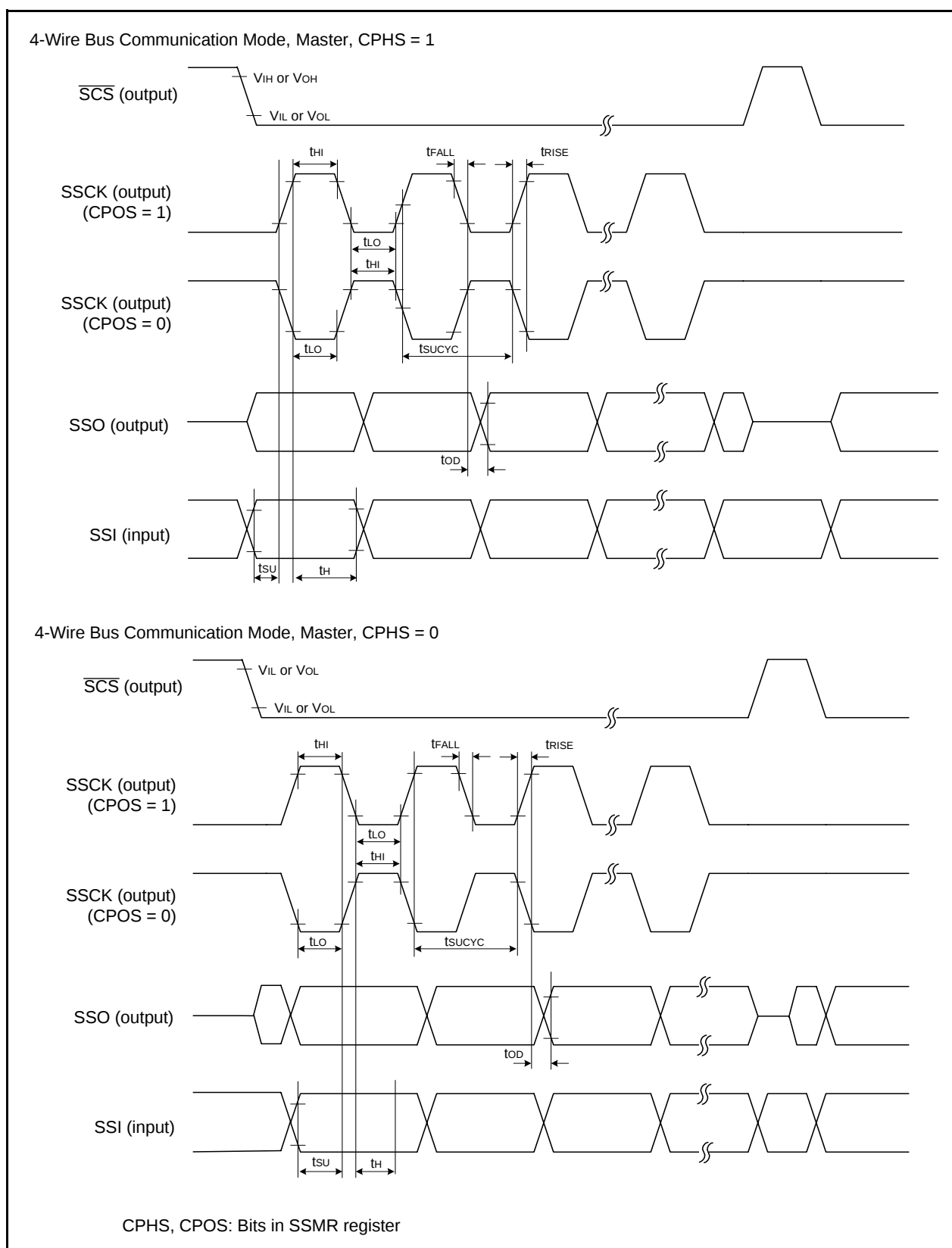


Figure 5.4 I/O Timing of Synchronous Serial Communication Unit (SSU) (Master)

Table 5.16 Timing Requirements of I²C bus Interface (1)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _{SCL}	SCL input cycle time		12t _{cy} c + 600 (2)	–	–	ns
t _{SCLH}	SCL input “H” width		3t _{cy} c + 300 (2)	–	–	ns
t _{SCLL}	SCL input “L” width		5t _{cy} c + 500 (2)	–	–	ns
t _{sf}	SCL, SDA input fall time		–	–	300	ns
t _{SP}	SCL, SDA input spike pulse rejection time		–	–	1t _{cy} c (2)	ns
t _{BUF}	SDA input bus-free time		5t _{cy} c (2)	–	–	ns
t _{STAH}	Start condition input hold time		3t _{cy} c (2)	–	–	ns
t _{STAS}	Retransmit start condition input setup time		3t _{cy} c (2)	–	–	ns
t _{STOP}	Stop condition input setup time		3t _{cy} c (2)	–	–	ns
t _{SDAS}	Data input setup time		1t _{cy} c + 40 (2)	–	–	ns
t _{SDAH}	Data input hold time		10	–	–	ns

Notes:

1. V_{CC} = 1.8 to 5.5 V, V_{SS} = 0 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. 1t_{cy}c = 1/f₁(s)

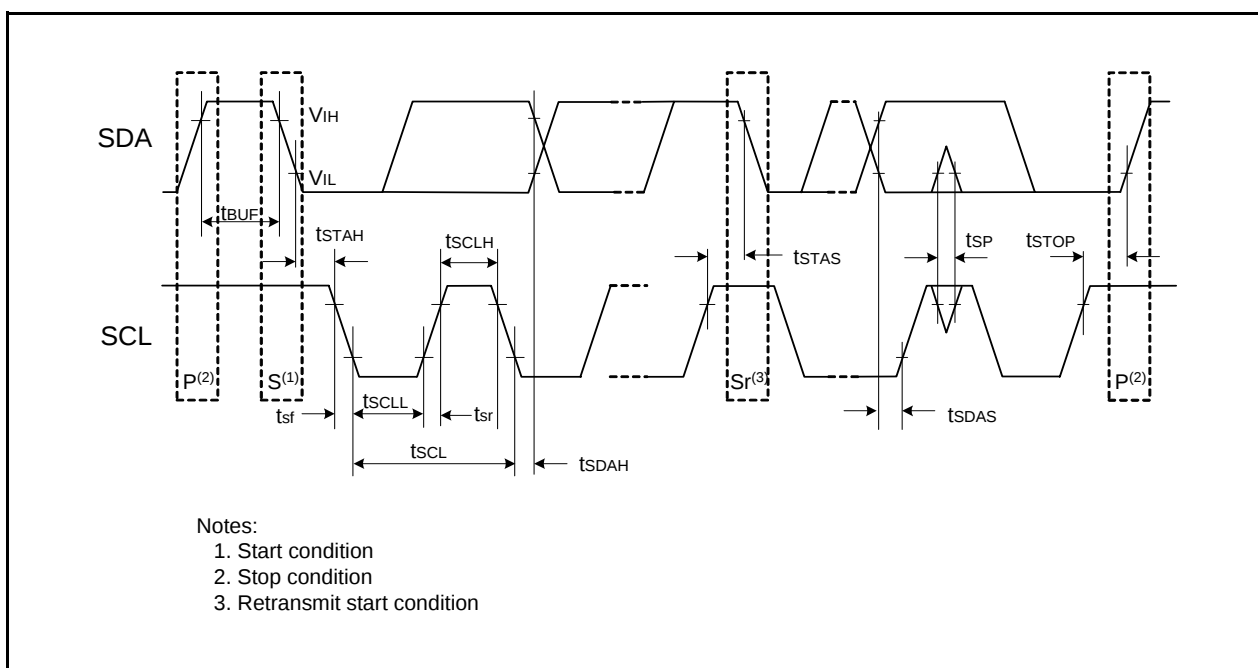
**Figure 5.7** I/O Timing of I²C bus Interface

Table 5.17 Electrical Characteristics (1) [$4.2\text{ V} \leq V_{CC} \leq 5.5\text{ V}$]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Other than XOUT	Drive capacity High V _{CC} = 5 V	I _{OH} = -20 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity Low V _{CC} = 5 V	I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
		XOUT	V _{CC} = 5 V	I _{OH} = -200 μ A	1.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Other than XOUT	Drive capacity High V _{CC} = 5 V	I _{OL} = 20 mA	—	—	2.0	V
			Drive capacity Low V _{CC} = 5 V	I _{OL} = 5 mA	—	—	2.0	V
		XOUT	V _{CC} = 5 V	I _{OL} = 200 μ A	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT3, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRCTRG, TRCCLK, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.1	1.2	—	V
		RESET			0.1	1.2	—	V
I _{IH}	Input "H" current		V _I = 5 V, V _{CC} = 5.0 V		—	—	5.0	μ A
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 5.0 V		—	—	-5.0	μ A
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 5.0 V		25	50	100	k Ω
R _{FXIN}	Feedback resistance	XIN			—	0.3	—	M Ω
R _{FXCIN}	Feedback resistance	XCIN			—	8	—	M Ω
V _{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

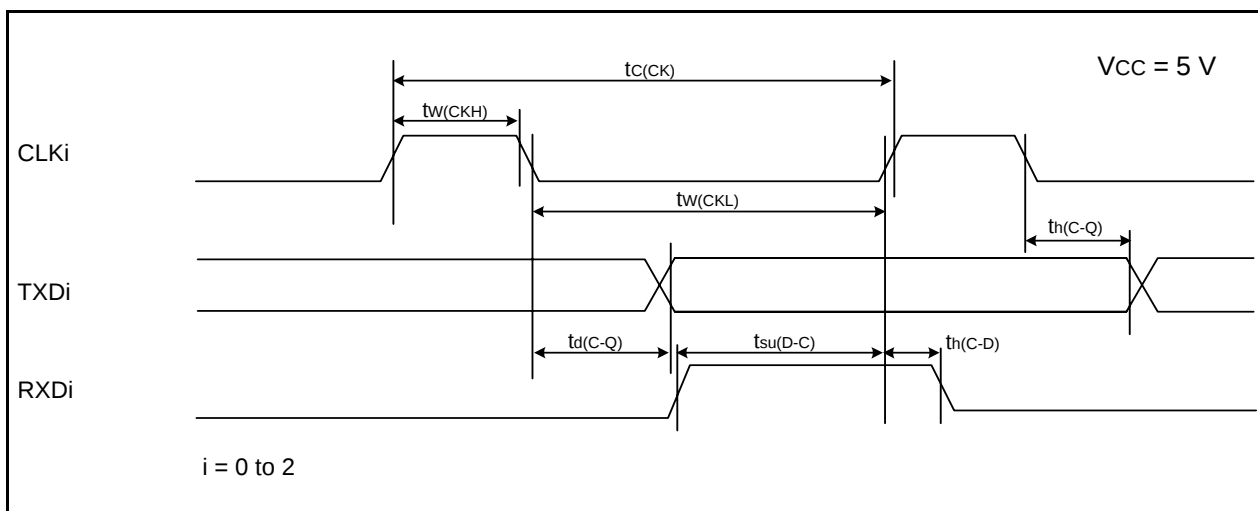
Note:

1. $4.2\text{ V} \leq V_{CC} \leq 5.5\text{ V}$ and T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.21 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200	—	ns
$t_{w(CKH)}$	CLKi input "H" width	100	—	ns
$t_{w(CKL)}$	CLKi input "L" width	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	50	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	50	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

i = 0 to 2

**Figure 5.10 Serial Interface Timing Diagram when Vcc = 5 V****Table 5.22 External Interrupt $\overline{INTi}$ (i = 0, 1, 3) Input, Key Input Interrupt $\overline{Kli}$ (i = 0 to 3)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INTi}$ input "H" width, $\overline{Kli}$ input "H" width	250 (1)	—	ns
$t_{w(INL)}$	$\overline{INTi}$ input "L" width, $\overline{Kli}$ input "L" width	250 (2)	—	ns

Notes:

1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency $\times$ 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency $\times$ 3) or the minimum value of standard, whichever is greater.

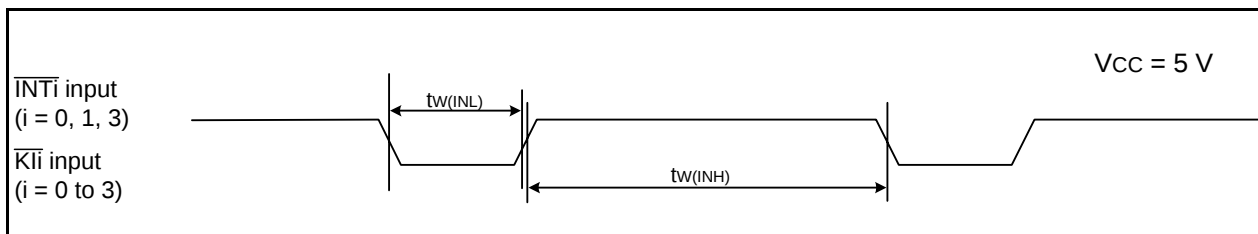
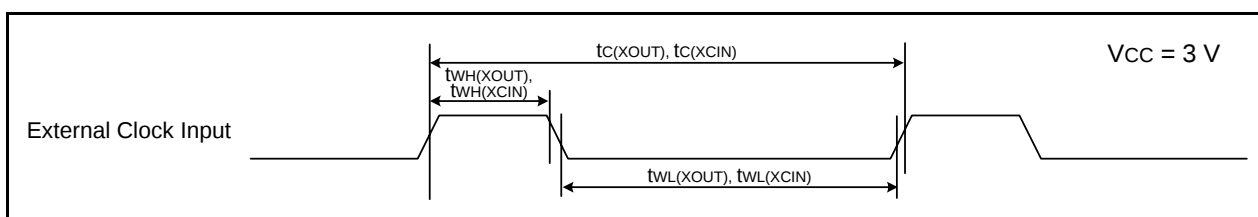
**Figure 5.11 Input Timing Diagram for External Interrupt $\overline{INTi}$ and Key Input Interrupt $\overline{Kli}$ when Vcc = 5 V**

Table 5.24 Electrical Characteristics (4) [$2.7\text{ V} \leq V_{CC} < 3.3\text{ V}$]
($T_{opr} = -20\text{ to }85^{\circ}\text{C}$ (N version) / $-40\text{ to }85^{\circ}\text{C}$ (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
I _{CC}	Power supply current ($V_{CC} = 2.7\text{ to }3.3\text{ V}$) Single-chip mode, output pins are open, other pins are V _{SS}	High-speed clock mode	—	3.5	10	mA
		High-speed on-chip oscillator mode	—	1.5	7.5	mA
		High-speed on-chip oscillator mode	—	7.0	15	mA
		Low-speed on-chip oscillator mode	—	90	390	μA
		Low-speed clock mode	—	80	400	μA
		Wait mode	—	15	90	μA
		Stop mode	—	2.0	5.0	μA

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 3\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^{\circ}\text{C}$)****Table 5.25 External Clock Input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{XOUT})$	XOUT input cycle time	50	–	ns
$t_{WH}(\text{XOUT})$	XOUT input “H” width	24	–	ns
$t_{WL}(\text{XOUT})$	XOUT input “L” width	24	–	ns
$t_c(\text{XCIN})$	XCIN input cycle time	14	–	μs
$t_{WH}(\text{XCIN})$	XCIN input “H” width	7	–	μs
$t_{WL}(\text{XCIN})$	XCIN input “L” width	7	–	μs

**Figure 5.12 External Clock Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.26 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRAIO})$	TRAIO input cycle time	300	–	ns
$t_{WH}(\text{TRAIO})$	TRAIO input “H” width	120	–	ns
$t_{WL}(\text{TRAIO})$	TRAIO input “L” width	120	–	ns

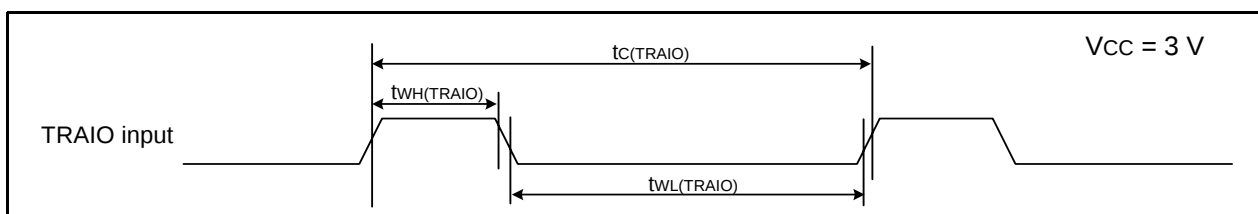
**Figure 5.13 TRAIO Input Timing Diagram when $V_{CC} = 3\text{ V}$**

Table 5.29 Electrical Characteristics (5) [$1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$]

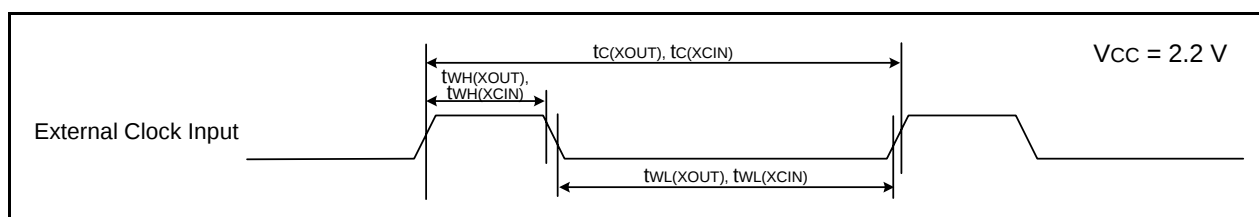
Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Other than XOUT	Drive capacity High	I _{OH} = −2 mA	V _{CC} − 0.5	−	V _{CC}	V
			Drive capacity Low	I _{OH} = −1 mA	V _{CC} − 0.5	−	V _{CC}	V
		XOUT		I _{OH} = −200 μA	1.0	−	V _{CC}	V
V _{OL}	Output "L" voltage	Other than XOUT	Drive capacity High	I _{OL} = 2 mA	−	−	0.5	V
			Drive capacity Low	I _{OL} = 1 mA	−	−	0.5	V
		XOUT		I _{OL} = 200 μA	−	−	0.5	V
V _{T+} −V _{T−}	Hysteresis	INT0, INT1, INT3, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRCTRG, TRCCLK, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.05	0.20	−	V
		RESET			0.05	0.2	−	V
I _{IH}	Input "H" current		V _I = 2.2 V, V _{CC} = 2.2 V		−	−	4.0	μA
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 2.2 V		−	−	−4.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 2.2 V		70	140	300	kΩ
R _{FXIN}	Feedback resistance	XIN			−	0.3	−	MΩ
R _{FXCIN}	Feedback resistance	XCIN			−	8	−	MΩ
V _{RAM}	RAM hold voltage		During stop mode		1.8	−	−	V

Note:

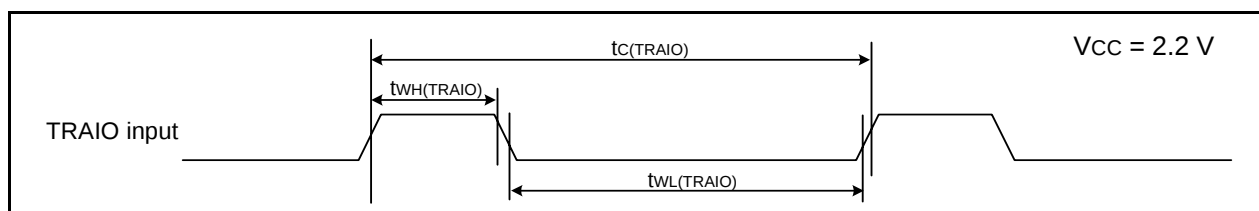
1. $1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$ and T_{opr} = −20 to 85°C (N version) / −40 to 85°C (D version), f(XIN) = 5 MHz, unless otherwise specified.

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 2.2\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^\circ\text{C}$)****Table 5.31 External Clock Input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	200	–	ns
$t_{WH(XOUT)}$	XOUT input “H” width	90	–	ns
$t_{WL(XOUT)}$	XOUT input “L” width	90	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

**Figure 5.16 External Clock Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.32 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	500	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	200	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	200	–	ns

**Figure 5.17 TRAIO Input Timing Diagram when $V_{CC} = 2.2\text{ V}$**

REVISION HISTORY	R8C/33C Group Datasheet
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Rev.	Date	Description	
		Page	Summary
0.01	Sep. 01, 2009	–	First Edition issued
1.00	Aug. 24, 2010	All 4 26 to 52	“Preliminary” and “Under development” deleted Table1.3 revised “5. Electrical Characteristics” added

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General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

- The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.